Panasonic INDUSTRY

Drop impact resistance
Underfill reinforcement
Sidefill reinforcement

LEXCM DF

CV5313 CV5314

For secondary mounting reinforcement drop impact resistance liquid encapsulant

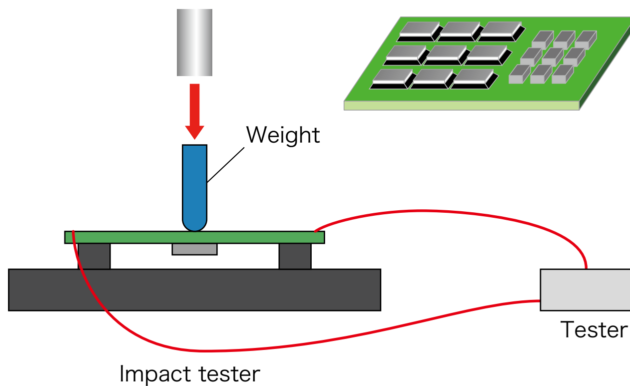
Applications
IC Package/Mobile
LSI package and SSD for mobile devices such as notebook PC, digital camera, mobile phones, smartphone and tablet PC.

Protection of "brain" of mobile terminal from drop impact. Underfill/Sidefill reinforcement material when BGA/CSP is mounted.

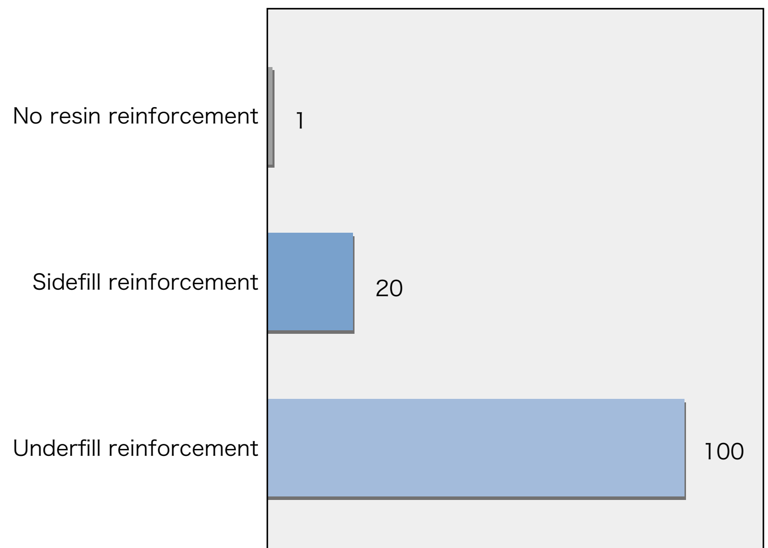
Comparison of impact test evaluations

Test conditions

Strain amount	3000μST (Weight 50g 30cm drop)
BGA	W14mm×D14mm×H1.2mm
Board	W35mm×D70mm×H0.6mm



Number of times of dropping before cracking occurs



General properties

Item	Unit	LEXCM DF CV5313 (Underfill)	LEXCM DF CV5314 (Underfill)
Viscosity (25℃)	Pa・s	2	130
Thixotropic index	—	1.2	3.5
Gelation time (150℃)	sec	50	70
Curing condition	—	120℃ 5min	120℃ 5min
Tg	℃	105	80
C.T.E. (α1)	ppm/℃	70	35
Flexural modulus	GPa	3	7

Please see our website for Notes before you use.

The above data are typical values and not guaranteed values.

industrial.panasonic.com/ww/electronic-materials

Panasonic Industry CV5313

Panasonic Industry Co., Ltd. Electronic Materials Business Division

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